

Supplemental

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	87	interconnect and ((cobalt or nickel) with via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
L2	87	L1 and metal	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
L3	87	L2 and layers	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
L4	47	L3 and (electroless adj deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
L5	47	L4 and ((cobalt or nickel) near\$3 via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
L6	47	L5 and (electroless adj deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
L7	1301	257/762.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:07
L8	1403	257/750.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:12
L9	4056	257/758.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:15
L10	0	(air adj gap) and interconnect and ILD and ((cobalt or nickel) with via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:19
L11	0	(air adj gap) and interconnect and ((cobalt or nickel) with via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:20

EAST Search History

L12	31	(air adj gap) and interconnect and ((cobalt or nickel) with via) and (electroless with deposition)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:20
L13	0	(apparatus and ((first adj layer) with interconnect) and ((second adj layer) with interconnect) and ((second adj layer) with sublayer) and (sublayer with ILD) and (sublayer with air) and ((third adj layer) with (air adj gap)) and (shunt with (first adj material)) and (shunt with interconnects) and (material with electromigration)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:24
L14	0	(apparatus and ((first adj layer) with interconnect) and ((second adj layer) with interconnect) and ((second adj layer) with sublayer) and (sublayer with ILD) and (sublayer with air) and ((third adj layer) with (air adj gap)) and (shunt with (first adj material)) and (shunt with interconnects) and (material with electromigration))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:24